

MIL-PRF-38534E - SUMMARY OF CHANGES

The following table summarizes changes to **MIL-PRF-38534** revision D that have been made to generate **Revision E** dated **6 Jan 03**

Paragraph	Change	Reason	Page Number
1.1 Scope	Change “insuring” to “ensuring”	Correction	1
1.2 Description of this specification	Change “insure” to “ensure”	Correction	2
1.2 Description of this specification (2 nd paragraph)	Delete “Manufacturers who were ... quality management program”	Clarification/update	2
1.2 Description of this specification (2 nd paragraph)	Change “Appendix B has been ... with Appendix A.” to “Appendix B is not currently being used.”	Clarification/update	2
1.2 Description of this specification (2 nd paragraph)	Delete “Manufacturers already certified ... the Appendix C verifications.”	Clarification/update	2
1.2 Description of this specification (2 nd paragraph)	Change “Appendix D has been deleted.” to read “ Appendix D is not currently being used”	Clarification/update	2
1.3.3 Class G	Add “confidence”	Clarification	2
1.3.3 Class G	Change “lowered” to “possibly lower”	Clarification	2
1.3.4 Class E	Change “insure” to “ensure”	Correction	2
1.3.5 Class D	Change “reduced” to “possibly lower”	Clarification	2
2.1 Government specification and standard	Change to read Government specification, standard, and handbooks. Change “Military” to Department of Defense”	Format change to agree with the general guidelines.	3
2.1 Government specifications and standards	Add reference to Web Sites for source of obtaining military documents.	Additional Resources Available	3
3.3 Performance requirements for Class G devices	Change “insure” to “ensure”	Correction	4
3.4 Performance requirements for Class E devices	Add “Manufacturers of these devices shall be fully certified in accordance with this specification” as next to last sentence.	Further explanation of information found in Table I.	4
3.6 Performance requirements for RHA devices	Add last sentence “Detailed information for producing and acquiring RHA devices can be found in JEDEC publication JEP133.”	Additional resources available	4
Table 1, Note 2/	Change “is” to “are”	Correction	5
3.7 General	Change “Monolithic microcircuits may ... of this specification.” to “ Monolithic microcircuits may be built to the Class K, H, G, E, or D performance requirements of this specification, however, monolithic microcircuits offered in compliance with this specification shall be specified on a Standard Microcircuit Drawing (SMD).”	Clarification	5
3.7 General	Change “Class K or H certification ...” to “Class K, H, G, E, or D certification...”	Clarification	5

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3.7.1 Implementation of this specification	Delete "his"	Correction	6
Table II. Implementation Summary	Change "Same as above" to "The exception shall be documented in the applicable acquisition document. Product is classified as Class E"	Clarification	6
3.7.5.8.2 Electrostatic discharge (ESD) sensitivity id	Add "≥" to the ESD Class designator number 3	Correction	9
4.1 General verification	Change "insuring" to "ensuring"	Correction	10
4.3 Baseline process flows	Change "process" to "processes"	Correction	10
4.5.1.1 On-site verification	Delete "documented"	Correction	11
4.5.2.3 Class E listing	Add new paragraph stating "Class E listing is granted upon qualification . . ."	Add precaution	11
6.2.1	Add new paragraph "e" stating "Requirements for Resistance of Soldering Heat."	Add requirements to consider the item's heat resistance to solder applications.	12
6.3.13 Design Activity	Add new paragraph "The organization specifies the device design parameters, layout, materials of construction, elements, sources, etc."	Clarification	13
6.3.13 - 6.3.47	Renumber paragraphs as 6.3.14 – 6.3.48.	Added new 6.3.13	13-16
6.3.22a -d	Renumber referenced paragraphs	Clarification	14
6.3.24 Inspection lots	Change "C" to "C3".	Allowed only for C3	14
6.3.29 Microcircuit	Add "active"	Clarification	14
6.3.30 Monolithic microcircuit	Add "(active)"	Clarification	14
6.3.42 Semiconductor element	Change "transistor or diode" to "Active semiconductor elements other than microcircuits . . ."	Expand definition to include other devices.	15
A.1.2 Technology Review Board (TRB) Option	Change "...controlled by a technology review board (TRB), which can modify..." to "...controlled by the TRB, which can modify..."	Clarification	18
A.1.2 Technology Review Board (TRB) Option	Change "are" to "may be"	Clarification	18
Appendix A Table of contents	Correct page numbers to agree with new pages.	Editorial	18
A.2.1 Government specification and standard	Change to read Government specification, standard, and handbooks. Change "Military" to Department of Defense"	Format change to agree with the general guidelines.	18
A.2.1 Government specifications and standards	Add reference to Web Sites for source of obtaining military documents.	Additional Resources Available	18
A.2.2 Non-Government publications	Add new paragraph listing ISO-14644-1 and ISO-14644-2 as applicable documents.	Additional resources available	19

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A.2.3 Order of Precedence	Change paragraph number from "A.2.2" to "A.2.3"	Added new paragraph A.2.2	19
A.3.1 Management responsibility	Change "see" to "ensure"	Clarification	19
A.3.2.2 Design, processing, manufacturing, and instructions	Reorder list	Clarification	19-20
A.3.2.2 b	Add "(A.3.2.3)"	Clarification	20
A.3.2.2 l	Add "(A.3.14)"	Clarification	20
A.3.2.4	Add "." (period at end of sentence)	Correction	20
A.3.3 Conversion of customer requirements	Add "and the next level assembly environment should be considered" after the phrase "requirements should be met".	Add requirements to consider the item's heat resistance to solder applications.	23
A.3.4 Design requirements	Add new paragraph "h" stating "Next level assembly environment (e.g. hand solder device or wave solder device to the next level assembly)."	Add requirements to consider the item's heat resistance to solder applications.	23
A.3.5.1.a Configuration Control – Class I	Add "radiation (when applicable)"	Radiation changes are major	24
A.3.5.1.b Configuration Control – Class II	Remove "In addition, for class K devices...affected"	Major change criteria will require Class II change notification with customer approval.	24
A.3.5.1.b Configuration control – Class II	Change "Class I" to "class I"	Correction	24
A.3.5.1 b Configuration Control – Class II	Change 2 nd sentence to read "Control procedures, records, and rational for the change should be kept available for review."	Clarification	24
A.3.5.1.c Configuration control – Class III	Change "insure" to "ensure"	Correction	24
A.3.13.1 Procedure in case of test equipment failure	Correct paragraph number from "A.3.1.3.1" to "A.3.13.1"	Correction	26
A.3.15.2 Cleanliness and atmosphere control in work areas	Replace Federal Standard 209 with ISO-14644-1 and reference ISO-14644-2 as a guide.	Fed Std 209 has been discontinued	27
A.3.16.1 Records to be maintained	Add "(ie MIL-STD-883 Method 5011...methods)."	Added example of records to be maintained	27

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A.3.16.1 Records to be maintained	Delete "Records should be ... and product traceability"	Correction	27
A.3.16.1 Records to be maintained	Add "Records pertaining to alternate methods, Group C testing QML, package evaluation, and 5011 testing shall be retained for 5 years (7 years for Class K) after the process or materials affected have been removed from the qualified flow."	Add requirement to keep records for certain items necessary for longer periods of time.	27
A.3.17.1.1 Self-audit representatives	Change "... audit checklist..." to "... audit checklist and deficiencies..."	Clarification	28
C.1.2 Description of Appendix C	Change "This approach is ... Periodic Inspection (PI) programs." to " This approach is a five-step approach consisting of an element evaluation program, a process control program, a screening program, a Conformance and Periodic Inspection program, and a qualification program."	Correction	30
Appendix C Table of contents	Correct page numbers to agree with new pages.	Editorial	30
C.2.1 Government specifications, standards and handbooks	Change "Military" to Department of Defense"	Format change to agree with the general guidelines.	31
C.2.1 Government specifications, standards and handbooks	Add reference to Web Sites for source of obtaining military documents.	Additional Resources Available	31
C.3.3 Microcircuit and semiconductor dice	In 2 nd sentence change "semiconductors which have been tested in accordance with MIL-PRF-19500" to read "semiconductor MIL-PRF-19500 qualified die or for MIL-PRF-38535 Class Q or V qualified die"	Add the requirement for 38535 die.	32
C.3.3 Micocircuit and semiconductor dice	In 3 rd sentence change "semiconductor devices which have been tested in accordance with MIL-PRF-19500" to read "semiconductor MIL-PRF-19500 qualified die or for MIL-PRF-38535 class V qualified die"	Clarification	32
C.3.3 Micocircuit and semiconductor dice	Delete "Element evaluation is not required for MIL-PRF-38534 qualified die."	Add the requirement for Class V die.	32
C.3.3.6.1 Sample selection and reject criteria	Change "Sample selection" to Microcircuit sample selection".	Clarification	33

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C.3.3.6.1 Sample selection and reject criteria	Add "Discrete semiconductor devices with oxide steps or expanded contacts shall be tested..."	Clarification	33
Table C-II. Subgroup 4 Mechanical Shock	Change condition "C" to condition "B".	Coordinate with Constant acceleration	34
Table C-II. Subgroup 6 SEM	Add "2077 1/" to method and change Quantity (accept number) to read See Method 2018 or 2077	Add the requirement to inspect discretes in accordance with MIL-STD-750	34
C.3.4.3.a Test sample preparation for subgroups 3 and 4	Change "will" to "may" Add "Electrical probe... assembly"	Clarification: Assembly not always required to evaluate an element. ie thickfilm chip resistor or capacitor	34
Table C-III Subgroup 3 Visual Inspection	Change method from "2017" to "2032".	2032 is the visual test method for passives	35
C.3.8 Package evaluation	Delete subgroup 5	Not needed because of subgroup 6 testing	39
C.3.8.1 Definition	Add "within a 6 month time frame"	Clarification of a plating lot	39
C.3.8.2.a	Remove "initial"	The term "initial" has no meaning	39
C.3.8.2.b	Delete subgroup 5	Not needed because of subgroup 6 testing	39
C.3.8.2.d	Add paragraph "d" stating "Covers require only Subgroups 1 and 6 of Table C-VI."	Clarify requirement for covers.	39
C.3.8.5 Subgroups 5 and 6	Change "Subgroups 5 and 6" to "Subgroup 6" (two places)	Moisture resistance has been deleted	39
Table C-VI Subgroup 3 Lead integrity	Add "B1 for rigid leads" as a condition for method 2004.	Rigid leads use condition B1	39
Table C-VI Subgroup 3 Lead integrity	Delete "and rigid leads" as a condition for method 2028	Rigid leads use condition B1	39
Table C-VI Subgroup 5	Delete subgroup 5 from table	Moisture resistance test has been deleted based on data that it is redundant to subgroup 6 salt atmosphere testing	39
C.3.9.3 Subgroup 1	Delete "This is a 100% incoming screen."	Unnecessary	40
C.3.9.4 Subgroup 2	Delete "This is a 100% incoming screen."	Unnecessary	40
C.3.9.5 Subgroup 3	Delete "This is a 100% incoming screen."	Unnecessary	40
C.3.9.7.b	Change "is" to "if"	Correction	40
C.3.9.8 Subgroup 7	Add "or equivalent, (See Paragraph C.6.3.2.6 for examples of equivalent conditions)".	Other bake options exist in 38534.	40

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C3.10 Adhesive evaluation	Change paragraph heading from “Adhesive evaluation” to read “Polymeric material evaluation” and change “ polymeric adhesives” to Polymeric materials.”	Correction	41
C.5.2 General	Add paragraph “f” stating “Tests will be performed in the order specified in Table C-IX, except as specified in C.5.11 and C.5.12.”	Clarification: X-Ray inspection can be performed any time after PIND – minimizes device handling	43
C.5.3 Preseal burn-in test	Delete “and performance requires the approval of the acquiring activity”.	Approval is not necessary	43
C.5.4 Nondestructive bond pull test for Class K devices	Change Class “H” to “Class H G,D, or E”.	Allow delivery of product to a lower class that fail non destruct bond pull.	43
C.5.5 Internal Visual Inspection	Remove “dry”	A controlled environment is all that is required.	43
C.5.7 Particle impact noise detection (PIND) test	Add “For Class K and Class H devices, condition A will be used unless otherwise specified.”	Class K community requires condition A.	44
C.5.9.1 General	Remove sections under C.5.9.5.1 and insert into the General paragraph, C.5.9.1 (see paragraphs c, e, f, and g)	Clarification of the imbedded BI requirements	44
C.5.9.1 General	Renumber paragraph “c” as “d”.	Added new paragraph c	44
C.5.9.4 Lots resubmitted for burn-in	Add “(e.g. if the PDA...if less than 20%.)” Also add “Failure analysis for other than Class K is not required.”	Clarification when a lot can be resubmitted to BI without a FA	45
C.5.9.5 Burn-in acceptance criteria	Add “without performing a resubmitted BI”	Clarification that resubmitted BI is not required if pattern FA is used.	45
C.5.9.5.1 General	Remove these requirements that pertain “in general” from this “specific area” and insert them into paragraph C.5.9.1.	These burn-in requirements are general and not specific to this area. They should be located in general requirements criteria.	45
C.5.9.5.3.1 Pattern failure option, Class H	Change the words “failure pattern” to read “pattern failure”. (7 places)	Clarification of the term to match the paragraph title.	45-46
C.5.11.b	Change “will” to “may”.	Clarification	46
C.5.12 Radiography for Class K devices	Add “Radiographic Inspection can be performed anytime after PIND”.	Clarification	47
Table C-IX PIND Test	Add “Class H or K” next to PIND Condition A. Also add Condition A shall be used for Class H or K, unless otherwise specified.”	Tie into paragraph C.5.7	47
Table C-IX Electrical Test	Change test type to read “Pre-Burn-in Electrical”.	Tie into para C.5.9.1.a	47
C.6.2 General	Delete “at the time of contract negotiation and acceptance” from the first sentence	Selection of a flow is often done before contract award	48

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C.6.2.1 Inspection lots	Add new paragraph to read "Inspection lots consist of a quantity of devices of a single device type (required for group A)or several different circuit types (allowed for groups B, C3, and D tests only) in ..."	Clarification	48
C.6.2.2 Inspection lot formation	Add new paragraph to read "Inspection lot formation is required if the inspection lot is to be formally accepted by the lot related CI or PI testing ..."	Clarification	48
C.6.2 General	Renumber subparagraphs C.6.2.1 - C.6.2.4 as C.6.2.3 - C.6.2.6	Added new subparagraphs C.6.2.1 and C.6.2.2	49
C.6.2.5 Data	Add the words "Date code".	Clarification of lot identification Code	49
C.6.2.5 Data	Change "will" to "shall".	Clarification	49
C.6.2.5 Data	Add the phrase "unless 100% recorded data is provided".	Attributes data should not be required if 100% recorded data is performed.	49
C.6.3.1.1 Group A general requirements	Add "Each of these three methods are equivalent, therefore, the manufacturer may choose to use any of the three."	Clarification	49
C.6.3.1.2.b	Change the words "to the required quantity (accept number)" to the phrase "in accordance with Table C-Xa"	Clarification to the correct table	49
C.6.3.1.3 In-line sample testing	Add "in accordance with Table C-Xa" in the second sentence	Clarification to the correct table	49
C.6.3.1.4 In-line verification testing	Add "In-line verification testing, generally, is performed in conjunction with final electrical tests at screening which satisfy the requirements of Group A testing and need not be repeated. Therefore, if the screening tests are performed with the verification defined here, the requirements of Group A have been met."	Clarification	50
C.6.3.1.4.c(2)	Revise first sentence wording to "Review actual testing or data of a ...".	Clarification of the process	50
C.6.3.1.4.c(2)	Add the phrase "or traceable to the lot" to end of paragraph.	allowance to review the data	50
C.6.3.2.3 PIND	Delete paragraph. .	Delete requirement for PIND as redundant	51
C.6.3.2.4 – C.6.3.2.8	Renumber paragraphs as C.6.3.2.3 – C6.3.2.7	Paragraph (PIND) removed	51
C.6.3.2.6 Solderability	Change "a 7 to 8 hour" to "an 8-hour (± 0.5 hour)"	To achieve consistency with MIL-STD-883,Method 2003	51
C.6.3.3 Group C Inspection	Delete "For QML qualification, refer to the qualifying activity."	Clarification	51
C.6.3.3 Group C Inspection	Add " For QML qualification, refer to section C.7 of this specification."	Clarification	51

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C.6.3.3.1.b	Change “see Appendix F “ to “see C.6.2.6”	Clarification - Tie into the non functional paragraph 52
C.6.3.3.1.c	Change “subgroups 1 and 2 when all of the following are met” to “subgroup 2 when all three criteria listed below are met.” Also add the statement “A sample of 22 devices shall be selected otherwise.”	Revise wording to match Table C-Xc... and defines when to use the 22(0) sample criteria. 52
C.6.3.3.1 General	Add subparagraph “d” stating “Tests will be performed in the order specified in Table C-Xc.”	Clarification 52
Table C-Xc subgroup 3	Delete “at 100 deg C” under 1018	The condition is specified in TM 1018 53
C.6.4.2.1 PIND test	Delete paragraph.	Delete requirement for PIND as redundant 54
C.6.4.2.2 – C.6.4.2.7	ReNUMBER as C.6.4.2.1 – C.6.4.2.6	Deleted paragraph (PIND) 54-55
C.6.4.2.2 Bond Strength	Add “Coupons which simulate actual production processes and materials may be used in lieu of actual product.”	Add the allowance to use coupons for group B, end of line testing. 54
Table C-Xb, PIND	Delete subgroup 2.	Delete requirement for PIND as redundant. 55
Table C-Xb	Change the Reference paragraphs to correspond to the new numbers given to C.4.2 subparagraphs.	Deletion of paragraph caused renumbering of others 55
C.6.4.4.4 Subgroups 2 and 3	Change “Subgroups 2 and 3” to “Subgroup 3”. (2 places)	Eliminate moisture resistance 56
Table C-Xd. Group D package related tests, lead integrity	Change “grip” to “grid”	Correction 56
Table C-Xd. Group D package related tests, lead integrity	Change method “2008” to “2028”	Correction 56
Table C-Xd. Group D package related tests, lead integrity	Delete “and rigid leads” Add “B1 for rigid leads”	B1 is used for rigid leads 56
Table C-Xd. Group D package related tests	Delete subgroup 2	Eliminate moisture resistance 56
C.7.6.2 Test samples	Change “DSCC Form EQC-42H” to “DSCC Form VQH-42H”.	Correct form number 58
C.7.6.2 Test samples	Add the phrase “or approved by the manufacturer’s TRB” at end of the second sentence.	Clarification 58
C.7.6.2 Test samples	Change “utilized” to “used”	Correction 58
C.7.6.2.2 Sample Selection	Delete sentence stating “In addition for group C, subgroup 3, a minimum of three electrical rejects or representative mechanical samples will be reserved.”	Not needed 58

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C.7.6.2.4 Nonfunctional Samples	Add the phrase "(e.g., for group C3, the rejects shall be subjected to group C1 prior to testing to group C3)".	Correction	58
C.7.6.4.6 Electrical Requirements	Add sentence "Data from Group A or final electrical test may be used as the initial end point electrical before starting subgroup 1 and 2."	Add allowance of performing test at Group A or final. This is when the testing is normally performed.	59
C.7.6.4.7 Steady-state life test	Add "and life test has previously been completed".	Clarification	59
C.7.6.4.8 Internal water vapor	In third sentence add the word "from the same lot" after the words " fully screened samples."	Clarification	59
C.7.6.4.8 Internal water vapor	Change "...submitted to the qualifying activity." to "...submitted to the qualifying activity for review and disposition."	Clarification	59
C.7.6.4.8 Internal water vapor	Add "If the sample size (accept number) of 5(1) is used and the sample contains one (1) failure, then the manufacturer shall perform an engineering evaluation on the failure. The evaluation, as an example, may include data to support materials used, element evaluation of materials, cure process time and temperature, bake-out process, seal chamber environment, seal process, adequacy of hermeticity test process, trend analysis, historical data review, or the consideration of other gases present. The engineering evaluation data will be available for review"	Add the requirement for an engineering review of the failed IWV device.	59
C.7.6.4.8 Internal water vapor	In last sentence change the phrase "same package" to read "same package type" and delete the phrase "that was processed and sealed in the same period."	Clarification	59
Appendix E Table of contents	Correct page numbers to agree with new pages.	Editorial	62
E.2.1 Government documents	Change to read Government specification, standard, and handbooks. Change "Military" to Department of Defense"	Format change to agree with the general guidelines.	62
E.2.1 DOD standards	Delete "MIL-STD-973 – Configuration Management"	Standard has been cancelled	62
E.2.1 Government specifications, standards, and Handbooks	Add reference to Web Sites for source of obtaining military documents.	Additional Resources Available	62
E.2.1.1	Delete this number and place information in E.2.1	Format change	62
E.3.1 Description of the rework limitations	Change "limitation" to "limitations"	Correction	62
E.3.1 Description of the rework limitations	Change "insure" to "ensure"	Correction	62
E.3.2.1.b	Delete the word "Touch-up" and the word "plating".	Correction	63
E.3.2.1.d (3)	Change "replaced or" to "reworked".	Correction	63

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E.3.2.1.d (3)	Add "or have been active trimmed/tuned".	Clarification	63
E.3.2.1 General Rework and repair provisions	Replace part "e" with new section for Class K devices that are reworked or repaired prior to sealed burn-in.	Clarification.	63
E.3.2.1 General Rework and repair provisions	Add new paragraph "f" for Class K devices that are reworked or repaired after sealed burn-in.	Clarification	64
E.3.2.1 General Rework and repair provisions	Renumber sections "f, g and h" as "g, h and I"	New section "f" added.	64
E.3.2.6 Seal rework	Add the word "hermetic" to the phrase "package seal".	Clarification	65
E.4.2.7.1 Internal element finishes	Add the words "element backing" in the examples.	Clarification.	67
E.4.2.7.1 Internal element	Change the phrase "lead bonding requirements" to "lead and element bonding requirements"	Clarification	67
E.4.2.7.1 Internal element finishes	Add the sentences "The use of pure tin is prohibited. Tin is considered pure if it contains less than 3% alloy material."	Clarification of pure tin as a prohibited material	67
E.4.2.7.3, d	Change "99.78" to "99.7"	Gold is available as 99.7% not 99.78%	68
E.4.2.10 Design and Construction	Add new section as follows: <u>Assembly Process Induced Environments</u> . When the next level assembly environment (e.g. solder attach to a board assembly) is specified, the design and construction shall be considered.	Add requirements to consider the item's heat resistance to solder applications.	68
E.5.1 Manufacturer controls	New paragraph as follows "The manufacturer is responsible for controlling all materials and processes involved in the production of devices compliant to this specification. Any change to the supplier, materials or processes, which may impact the reliability and performance of the final device, must be controlled and evaluated by the manufacturer. This may include documentation of all changes, additional testing of devices, and/or notification of customers and the qualifying activity. This includes obsolescence and availability issues."	Add requirements for the manufacturer to control changes that affect the device.	69
E.5.1 Class I, major changes	Change paragraph number to paragraph "E.5.2".	Added new paragraph E.5.1	69
E.5.2 Class I, major changes	Add " and provided to the qualifying activity for review and approval"	Emphasize that the qualifying activity must be involved in major changes.	69
E.5.2 Class I, major changes, subparagraph x	Delete "as defined in MIL-STD-973"	Standard has been cancelled	70

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E.5.2 Class I, major changes, subparagraph y	Add new "y" stating "For class K devices only, all class I and class II changes since the original base-line qualification (CI, PI, QML)."	Clarification	70
E.5.2 Class I, major changes, subparagraph z	Add new "z" stating "For radiation hardened devices only, all class I and class II changes since the original base-line qualification (CI, PI, QML)."	Clarification	70
E.5.2 Class I, major changes, subparagraph aa	Add new "aa" stating Change of element finish (e.g., palladium termination to gold, gold plated lead to nickel)." "	Clarification	70
Table E-1, c. Process/time/temp changes	Change "C2" to "B5".	Correction	70
Table E-1, d. Substrate mask design	Change "C4" to "C2"	Correction	70
Table E-1, m. Increase in substrate perimeter	Change "C3" to "C4".	Correction	71
Table E-1, t, Increase in lead count per package	Change note " <u>7</u> " to note " <u>6</u> "	Correction	71
Table E-1, x. Class I change	Delete "MIL-STD-973"	STD has been cancelled	72
Table E-1, y. For Class K devices only	Add new section "y".	Clarification	72
Table E-1, z. For Radiation Hardened Devices only	Add new section "z".	Clarification of RHA major change requirements.	72
Table E-1, aa. Change of element finish material	Add new section "aa"	Clarification of change in finish	72
Table E-1, Notes	Delete Note " <u>5</u> ", renumber subsequent notes.	Correction	72
Appendix F Table of contents	Correct page numbers to agree with new pages.	Editorial	73
F.2.1 Government documents	Change to read Government specification, standard, and handbooks. Change "Military" to Department of Defense"	Format change to agree with the general guidelines.	73
F.2.1.1	Delete this number and place information in E.2.1	Format change	73
F.2.1 Government specifications, standards and handbooks	Add reference to Web Sites for source of obtaining military documents.	Additional Resources Available	73
G.2 Applicable Documents	Delete the words "This section does not apply" and add paragraph G.2.1 Government specifications, standards, and handbooks.	Additional Resources Available	75

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G.2.1 Government specifications, standards, and handbooks	Add as applicable MIL-HDBK-814 and MIL-HDBK-815, and how to obtain documents.	Additional Resources Available 75
G.2.2 Non-Government publications	Add as applicable: Electronic Industries Alliance; JEP133, JESD57, and JESD89 as well as American Society for Testing and Materials (ASTM); F1192 and F1892	Additional Resources Available 75-76
G.3.1 Performance Requirements for RHA devices	Replace MIL-T-1019 with MIL-STD-883 methods 1017, 1019, 1020, 1021, 1022, 1023, and 1032.	Required corrections 76
G.3.1 Performance Requirements for RHA devices	Correct JEDEC 57, JEDEC 133, ASTM-F-1843, ASTM 1032, and ASTM 1192 to JESD 57, JEP 133, ASTM-F-1032, and ASTM-F-1192 respectively. Delete ASTM-F-1843 and MIL-T-1017.	Clarification 76